Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

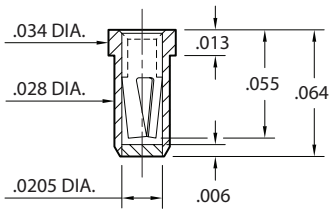
PIN RECEPTACLES

PIN RECEPTACLES
WITH ORGANIC FIBRE PLUG® SOLDER BARRIER
(SEE SPECIFIC CONTACT RANGE ON PAGES 250, 251 & 253)

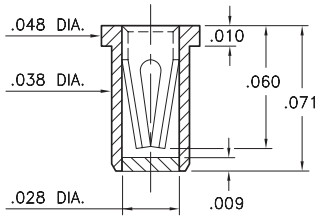
- These through-hole (tubular) receptacles are designed for hand, wave or reflow* soldering. The *ORGANIC FIBRE PLUG®* barrier prevents solder paste or flux from contaminating the spring contact.
- After soldering, the *OFP®* barrier is pushed out of the receptacle when the device is plugged in.
- All parts are available as discrete receptacles or supplied on carrier tape per EIA-481 to feed industry standard pick and place machines.

**Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The receptacles are placed into plated through-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated through-holes and achieve solder joints as reliable as wave soldering. The OFP® barrier prevents solder paste from being picked-up inside the contact during pick 'n place assembly. "Overprinting" paste on the solder mask can be used to adjust the volume of paste required to fill each hole.*

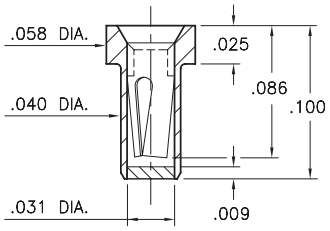
4428
4428-0-XX-XX-04-XX-10-0
Solder mount in Ø .032" max. PTH
#04 Contact for Ø .008" - .013" pins
Also available on 16mm wide carrier tape:
3,400 parts per 13" reel



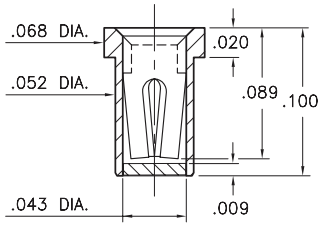
5359
5359-0-XX-XX-10-XX-10-0
Solder mount in Ø .043" ± .003" PTH
#10 Contact for Ø .012" - .017" pins
Also available on 16mm wide carrier tape:
3,000 parts per 13" reel



0577
0577-0-XX-XX-21-XX-10-0
Solder mount in Ø .045" ± .003" PTH
#21 Contact for Ø .015" - .022" pins
Also available on 12mm wide carrier tape:
3,000 parts per 13" reel



4015
4015-0-XX-XX-30-XX-10-0
Solder mount in Ø .057" ± .003" PTH
#30 Contact for Ø .015" - .025" pins
Also available on 8mm wide carrier tape:
5,500 parts per 13" reel



SPECIFICATIONS:

Shell Material: Brass Alloy 360, 1/2 Hard

Contact Material: Beryllium Copper Alloy 172, HT

Solder Barrier: Organic Fibre Plug®

Dimensions: Inches

Tolerances On: Lengths: ± .005
Diameters: ± .002
Angles: ± 2 °

RoHS-2 2011/65/EU

ORDER CODE: XXXX - 0 - XX - XX - XX - XX - XX - 0

BASIC PART #

SPECIFY PACKAGING:
43 Discrete Receptacles
67 Supplied on 13" Reels

SPECIFY SHELL FINISH:
01 200 µ" TIN/LEAD OVER NICKEL
◆ **80** 200 µ" TIN OVER NICKEL (RoHS)

CONTACT:
#04, #10, #21 or #30 CONTACT (DATA ON PAGES 250, 251 & 253)

SPECIFY CONTACT FINISH:
◆ **27** 30 µ" GOLD OVER NICKEL (RoHS)
02 100 µ" TIN/LEAD OVER NICKEL
◆ **84** 100 µ" TIN OVER NICKEL (RoHS)

Mill-Max Mfg. Corp. • 190 Pine Hollow Road, P.O. Box 300, Oyster Bay, NY 11771 • 516-922-6000 • Fax: 516-922-9253 • www.mill-max.com